

DESCRIPTION

Polyimide Tape w/Silicone Adhesive. A polyimide film with silicone adhesive designed for high temperature masking applications. For the protections of printed circuit board gold finger contacts during wave soldering. Custom slit to width

APPLICATION PROCESS

Used in electrical insulation applications meeting class H requirements. Release surface in fabrication of parts cured at elevated temperatures. Thin and conformable enabling masking of uneven surfaces. Wide operating temperatures range up to 500°F. Excellent electrical insulation. Removes cleanly without adhesive residue after exposure to heat/chemical. Excellent resistance to acids, oils, solvents.

MATERIAL DESCRIPTION

SIZE (width x length)	36 yd
COLOR	Amber
ADHESIVE TYPE	Pressure-Sensitive Tape
CONSTRUCTION	Single Coated
SELF WOUND	Yes
RELEASE LINER MATERIAL	N/A
RELEASE LINER THICKNESS	
WEIGHT	

TECHNICAL DATA

ADHESIVE LAYER	Silicone
BACKING/CARRIER MATERIAL	Polyimide Film
BACKING/ADHESIVE THICKNESS	1 mil
TOTAL THICKNESS	2.5 mil
ADHESION TO STEEL	600 g/inch
TENSILE STRENGTH	10 kg/inch
ELONGATION	greater than 55%
TEMPERATURE APPLICATION	
TEMPERATURE OPERATING	Resistance: 500°F

Surfaces to be bonded to should be dry, clean and free from oil and grease.

Typical shelf life is one (1) year from date of manufacture (DOM). Recommended storage conditions: 40-60% Humidity, 60°F to 80°F

Note: The information listed above has been obtained from controlled laboratory tests and is reliable, but should not be used for the purpose of writing specifications. It is offered in good faith, but without guarantee, as conditions and methods of use of our products are beyond our control. It is recommended that the prospective user determine the product suitability before adapting for commercial use.



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